

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0213222 A1 WU et al.

Jun. 27, 2024 (43) **Pub. Date:**

(54) SEMICONDUCTOR DEVICE PACKAGE AND METHOD OF MANUFACTURING THE SAME

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(21) Appl. No.: 18/426,124

(22) Filed: Jan. 29, 2024

Related U.S. Application Data

(63) Continuation of application No. 17/493,709, filed on Oct. 4, 2021, now Pat. No. 11,887,967, which is a continuation of application No. 16/779,249, filed on Jan. 31, 2020, now Pat. No. 11,139,274.

(60)Provisional application No. 62/799,701, filed on Jan. 31, 2019.

Publication Classification

(51) Int. Cl. (2006.01) H01L 25/065 H01L 21/02 (2006.01)(2006.01)H01L 21/768 H01L 23/31 (2006.01)

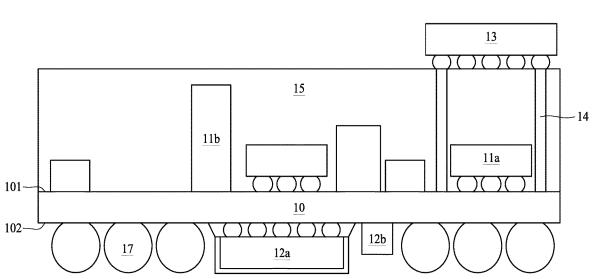
U.S. Cl. (52)CPC H01L 25/0657 (2013.01); H01L 21/02631

(2013.01); H01L 21/76838 (2013.01); H01L

23/3121 (2013.01)

(57)ABSTRACT

A semiconductor device package includes a substrate, a connection structure, a first package body and a first electronic component. The substrate has a first surface and a second surface opposite to the first surface. The connection structure is disposed on the firs surface of the substrate. The first package body is disposed on the first surface of the substrate. The first package body covers the connection structure and exposes a portion of the connection structure. The first electronic component is disposed on the first package body and in contact with the portion of the connection structure exposed by the first package body.



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